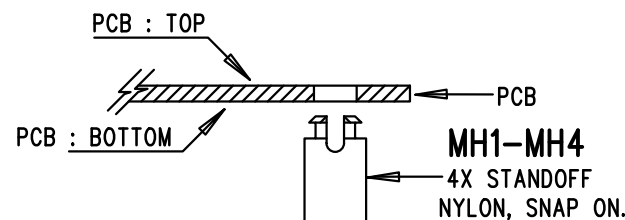


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	2ND PROTOTYPE	PINKESH S.	05-20-20

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNT AS SHOWN ON ASSEMBLY DRAWINGS.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



8. MARK EACH ASSEMBLY TYPE, SUFFIX, IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY. TYPE	U1A, U1B	SUFFIX
DC2969A-A	LTC4372	2
DC2969A-B	LTC4373	3

APPROVALS

PCB DES.	KIM T.	ANALOG DEVICES POWER BY LINEAR 2555 AUGUSTINE DRIVE SANTA CLARA, CA 95054 www.analog.com	
APP ENG.	PINKESH S.		
		TITLE: TOP ASSEMBLY DRAWING	
		LOW QUIESCENT CURRENT DUAL IDEAL DIODES	
		SIZE	IC NO. LTC4372HMS8, LTC4373HMS8
		N/A	REV. 2
SCALE = NONE		DEMO CIRCUIT 2969A FILENAME: DC2969A-2.PCB SHT 1 OF 2	